

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS IV)

# **TPCS8104**

Lithium Ion Battery Applications Notebook PC Applications Portable Equipment Applications

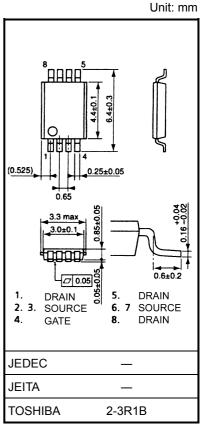
- Small footprint due to small and thin package
- Low drain-source ON resistance:  $RDS(ON) = 8.1 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance:  $|Y_{fs}| = 23 S$  (typ.)
- Low leakage current:  $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -30 \text{ V)}$
- Enhancement-mode:  $V_{th} = -0.8 \text{ to } -2.0 \text{ V (V}_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA})$

#### **Maximum Ratings (Ta = 25°C)**

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	-30	V	
Drain-gate voltage (Ro	$_{\rm SS} = 20 \text{ k}\Omega$ )	$V_{DGR}$	-30	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	-11	А	
Drain current	Pulse (Note 1)	$I_{DP}$	-44		
Drain power dissipatio	n (t = 10 s) (Note 2a)	$P_{D}$	1.1	W	
Drain power dissipatio	n (t = 10 s) (Note 2b)	P <sub>D</sub>	0.6	W	
Single pulse avalanche	e energy (Note 3)	E <sub>AS</sub>	31.5	mJ	
Avalanche current		I <sub>AR</sub>	-11	Α	
Repetitive avalanche (N	energy lote 2a) (Note 4)	E <sub>AR</sub>	0.11	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature r	ange	T <sub>stg</sub>	-55 to 150	°C	

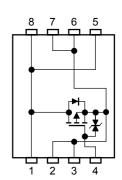
Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.035 g (typ.)

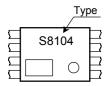
### **Circuit Configuration**



#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	114	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	208	°C/W

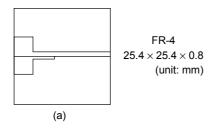
### Marking (Note 5)

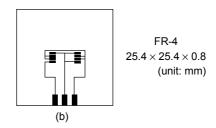


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

(a) Device mounted on a glass-epoxy board (b) Device mounted on a glass-epoxy board (b)





Note 3:  $V_{DD} = -24 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial), L = 0.2 mH,  $R_G = 25 \Omega$ ,  $I_{AR} = -11 \text{ A}$ 

Note 4: Repetitive rating: pulse width limited by maximum channel temperature

Note 5:  $\circ$  on lower right of the marking indicates Pin 1.

shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

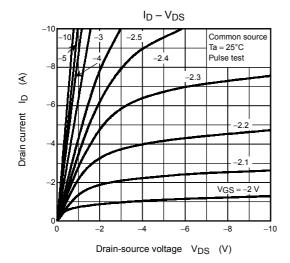
# Electrical Characteristics (Ta = 25°C)

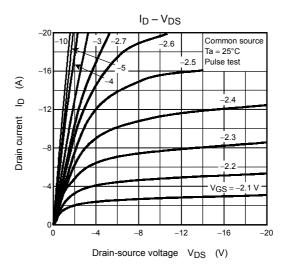
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage curren	t	I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$		_	±10	μΑ
Drain cut-OFF curre	nt	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μΑ
Drain-source breakd	own voltage	V <sub>(BR)DSS</sub>	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	_	_	V
Drain-source breakdown voltage		V <sub>(BR)DSX</sub>	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-15	_		٧
Gate threshold voltage	ge	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	-0.8     —     -2.0       —     12     18       —     8.1     12       11     23     —		V	
Drain-source ON res	istance	Б	$V_{GS} = -4 \text{ V}, I_D = -5.5 \text{ A}$		12	18	mΩ
Diam-source On les	istarice	R <sub>DS</sub> (ON)	$V_{GS} = -10 \text{ V}, I_D = -5.5 \text{ A}$	10 -30150.82.0 - 12 18 - 8.1 12 11 23 5710 560 590 18 23 109 -	12	11122	
Forward transfer admittance		Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_D = -5.5 \text{ A}$	11	23		S
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	5710	_	pF
Reverse transfer capacitance		C <sub>rss</sub>		_	560	_	
Reverse transfer capacitance  Output capacitance		Coss		_	590	_	
	Rise time	t <sub>r</sub>	$V_{GS}$ $0 V$ $I_D = -5.5 A$		18		- ns
Switching time	Turn-ON time	t <sub>on</sub>	27.44 27.44 27.5 = 27.5 = 20.40 20	_	- ±10102.0 12 18 8.1 12 23 - 5710 - 560 - 18 23 - 109 - 396 - 396	_	
Switching time	Fall time	t <sub>f</sub>	. α	_	109	_	
	Turn-OFF time	t <sub>off</sub>	$V_{DD} \simeq -15 \text{ V}$ Duty \le 1%, t <sub>w</sub> = 10 \mus	_	396	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq -24 \text{ V}, V_{GS} = 10 \text{ V},$	_	107	_	
Gate-source charge 1		Q <sub>gs1</sub>	$I_D = -11 \text{ A}$	_	12		nC
Gate-drain ("miller")	charge	Q <sub>gd</sub>		_	20		

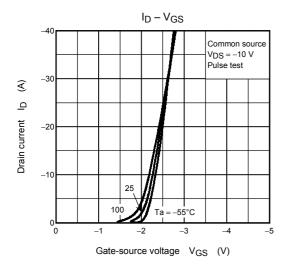
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

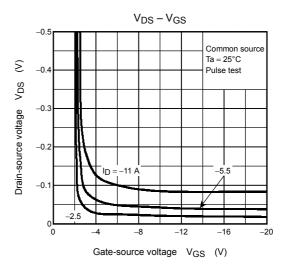
Characteri	stics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse	(Note 1)	I <sub>DRP</sub>	_	_	_	-44	Α
Forward voltage (diode)			V <sub>DSF</sub>	$I_{DR} = -11 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

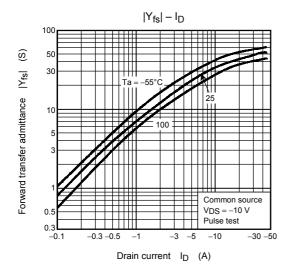
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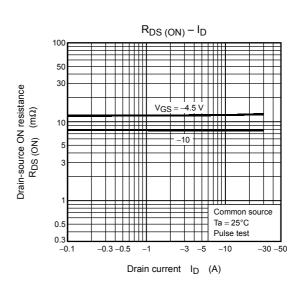




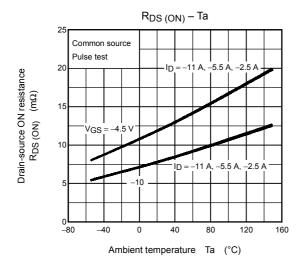


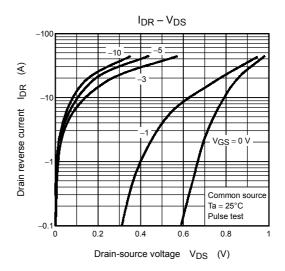


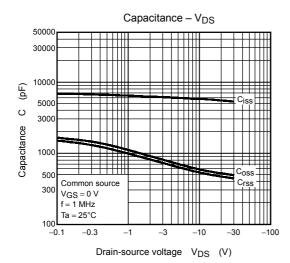


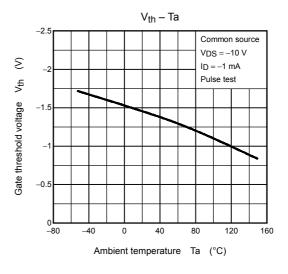


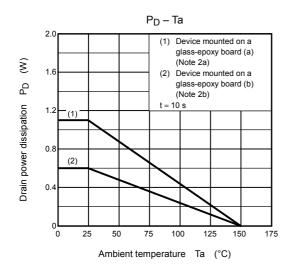
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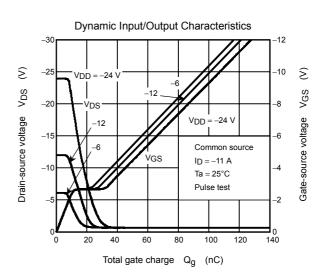






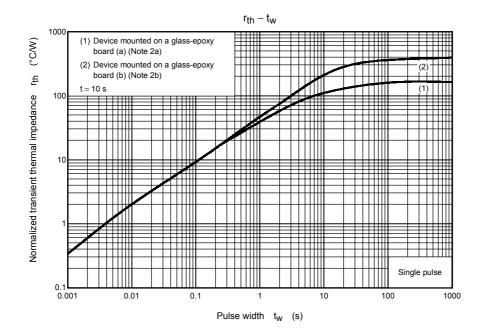


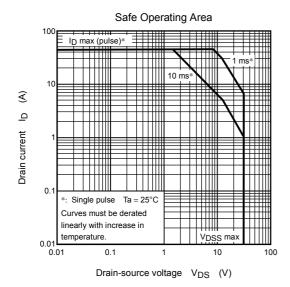




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6

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